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Request: May I kindly request you to submit your paper(s) and circulate the following CFP in your department, Software/Computer Science/ICT research groups, and all interested researchers who may be potential authors. All the publications will be in LNCS(Springer) as a book series of Computational Science and Its Applications: **ICCSA** and IEEE Xplore. Please visit the following site for more detail.

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If your paper is a theme paper and 10-16 pages long (LNCS Format), belongs/related to general and applications area of software engineering (e.g.-application or use of software/model/algorithms/tools/frameworks in clouds, IoT, healthcare, security, etc. and Software Intelligent systems), please submit it in Software Engineering process and applications (SEPA 2022). If you are working in any area related to quality issues of Software/Software engineering, consider Software Quality (ISSQ 2022) for your submission. Further, if your paper is a short session paper and up to 6-10 pages (in IEEE format), please select TTSDP 2022 for your submission.

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I hope and request your contribution.

Prof Sanjay Misra, Organizing Chair: SEPA 2022, ISSQ-2022, TTSDP-2022
ssopam@gmail.com,

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